Solder paste NP303-LD155-GQ

GENMA EUROPE

Product description

GENMA SMD solder paste – our NP303-LD155-GQ convinces with its outstanding contours stability after printing. The printed solder paste will not flatten out. The soldering process does not produce solder beads. The flux is kept at the soldering joint and does not spread on the PCB. Cleaning after soldering is not necessary. If necessary, residues can be easily removed. The solder paste can be soldered under air or nitrogen reflow.

Technical properties

	Specific value	Testing method
Alloy	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	
Melting temperature range	217 - 221	IEC61189-11
Powder size (µm)	22 - 38, type 4	IPC-TM-650-2.2.14.2
Viscosity (Pa · s)	180 ± 20	IPC-TM-650-2.4.34.3
Flux content (wt %)	10,5 ± 0,3	IPC-TM-650-2.3.34.1
Flux type	ROL1, no clean	IPC-J-STD-004B
Printing pitch (mm)	0,4	
Halide content (wt %)	0,04 ± 0,02	IPC-TM-650-2.3.35
Slump in print (mm)	≤ 0,2	IPC-TM-650-2.4.35
Slump in heat (mm)	≤ 0,3	IPC-TM-650-2.4.35 (150°C / 60sec)
Insulation resistance (Ω)	≥ 1 x 10^{11} (40°C 90 % r. L)	IPC-TM-650-2.6.3.3
Insulation resistance (Ω)	≥ 5 x 10^{8} (40°C 90 % r. L)	IPC-TM-650-2.6.3.3
Migration test	No migration	IPC-TM-650-2.6.14.1
Copper mirror test	No corrosion	IPC-TM-650-2.3.32
Packaging	Jar (0,5 kg) Semco cartridge (0,65 kg, 1,2 kg)	
Shelf life	6 months at 0-10°C	
Transport	keep cool	
Tempering the solder paste	Set to room temperature before opening to avoid condensation.	
Recommended printing speed (mm/s)	20 - 80	
Recommended temperature during print (°C)	25 ± 3	
Recommended relative humidity in % during print	50 ± 20	

Compliance

Dated 13.11.2025

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU.

Contains no substances (SVHC-list) more than threshold (0,1%) according to REACH legislation EG Nr.

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Contains no substances as defined by the Toxic Substance Control Act (TSCA) of the United States Environmental Protection Agency.

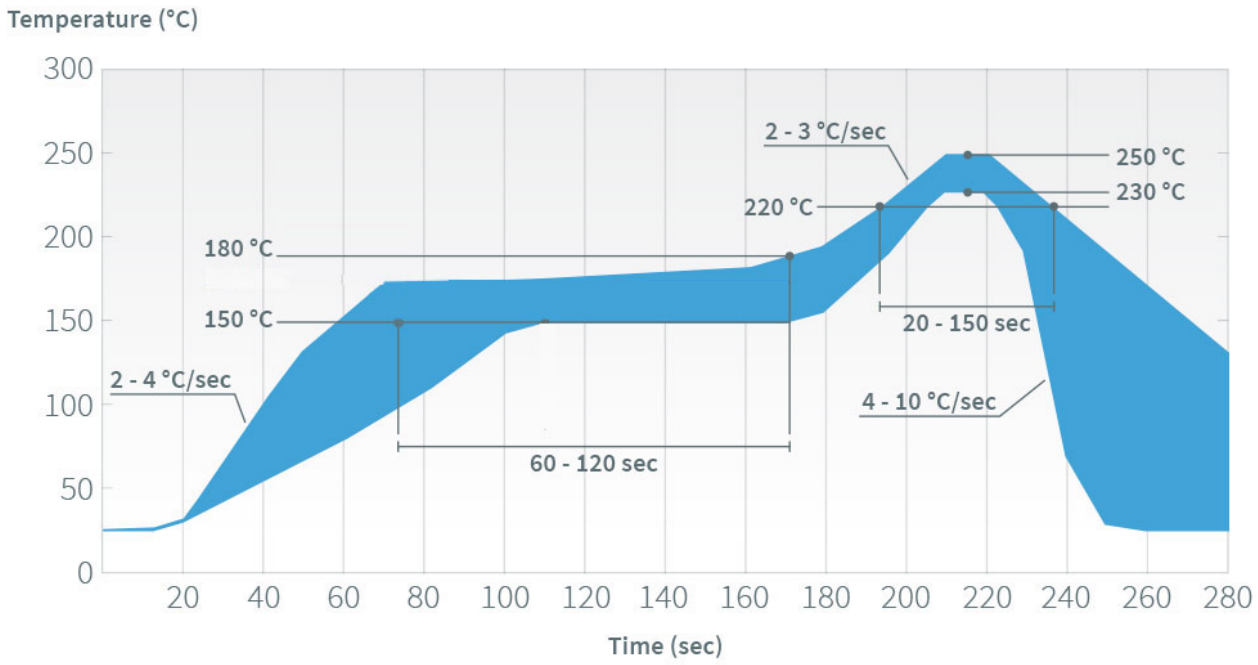
Contains no substances according to POP Regulation EU 2019/1021.

Contains no Per- and PolyFuluoroAlkyl Substances (PFAS).

Contains no phthalates or latex.

Contains no substances according to California Proposition 65.

Recommended Reflow Profile



Preheating

The temperature increase should be 2°C to 4°C/sec until the preheating zone is reached. If the temperature rises too quickly this may cause a running of the solder paste.

To achieve a temperature spread (Δt) on the circuit board that is as limited as possible, the temperature in the preheating zone should be between 150 and 180°C and the preheating time should be 60 to 120 seconds. If the temperature is too low or the preheating time too short, the temperature spread (Δt) on the circuit board will be too high. If the temperature is too high and the preheating time too long the activators will get lost which may lead to poor melting of the solder paste.

Reflow peak

We recommend keeping the temperature at 220°C for 20 to 150 seconds, if possible. If this is impossible, a temperature of up to 250°C can be maintained for a shorter period of time. It must be ensured, however, that the components are suited for the higher temperature.

Cooling down

The cooling rate should be between 4 and 10°C/sec. If the cooling rate is too low components may be displaced or come up and reduce the strength of the solder connections. If the cooling rate is too high, however, components can be damaged through thermal shock.

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